

REMARKS

With this Amendment, claims 3 and 4 are cancelled. Therefore, claims 1 and 2 are all the claims currently pending in this Application.

REMINDER: Information Disclosure Statement of February 6, 2006

As previously noted in the 1.111 Response of December 20, 2006, Applicants note that with the Office Action of September 20, 2006, the Examiner returned a copy of the PTO-SB-08 form submitted with the Information Disclosure Statement of February 6, 2006, but that the Examiner has crossed out all the references listed therein.

The Examiner has not remedied this situation with the current Office Action and has provided no explanation as to why the references were crossed out.

Applicants **again** respectfully request an explanation of why these references were crossed out and respectfully request that a duly signed *and initialed* copy of the PTO form be returned with the next Office communication, *without* the references crossed out.

Claim Amendments

With this Amendment, Applicants amend claim 1 to incorporate the limitations of claims 3 and 4. Claims 3 and 4 are cancelled. Entry of this Amendment is respectfully requested.

Prior Art Rejections

Claims 1-4 are rejected under 35 U.S.C. § 102(b) as allegedly unpatentable over Ikefuji (U.S. Patent 6,404,644). Applicants respectfully traverse this rejection.

Applicants submit that Ikefuji fails to disclose or suggest a broad section “for pressing out and spreading uniformly the semiconductor mounting paste for connecting to an IC chip is

formed in a part of the pad clearance gap,” and further fails to disclose or suggest “a thin film layer is formed in a center section of the broad section,” as recited in claim 1.

According to an embodiment of the present invention, a semiconductor mounting paste is used to attach an IC chip. The mounting paste has a viscosity which enables it to flow, and therefore, one or more semiconductor mounting paste guides is formed in a part of the pad clearance gap. The semiconductor mounting paste is disposed in the broad section, and the thin film is formed in a center portion of the broad section and is pressed out so that the paste is spread uniformly.

In contrast, in the first embodiment of Ikefuji, solder bumps disposed at precisely the locations of the terminals are used to connect the IC chip to the substrate. This solder is in no way disposed in a gap between terminals. Ikefuji clearly describes the goal of avoiding a short circuit of the coils 12, and if the solder were disposed between the terminals, this would cause a short circuit.

In the second embodiment of Ikefuji, an anisotropic film 19 is used to connect the IC chip to the substrate. This anisotropic film does not have a viscosity which enables it to flow, and therefore, no semiconductor mounting paste guide path is needed.

There is no disclosure or suggestion of any semiconductor mounting paste in either the third or fourth embodiment of Ikefuji.

Additionally, Ikefuji fails to disclose or suggest any thin film applied to any central portion of a broad section.

Therefore, in view of the above, Applicants submit that Ikefuji fails to anticipate claim 1 of this Application and that claim 2 is patentable at least by virtue of its dependence on claim 1.

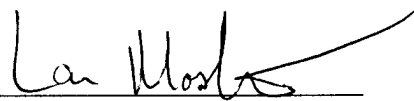
Applicants respectfully request that the rejection of claims 1 and 2 be reconsidered and withdrawn.

Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned attorney at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Laura Moskowitz
Registration No. 55,470

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: August 15, 2007